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**Dodson**

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(54) **HOUSING WITH DIRECTED-FLOW COOLING FOR COMPUTER**

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(52) **U.S. Cl.** ..... **361/695**; 361/687; 361/688; 361/689; 361/690; 174/16.1; 174/16.3; 165/80.3; 165/122; 454/184

(58) **Field of Search** ..... 361/687-695; 174/16.1, 16.3; 165/80.3, 122; 454/184

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(57) **ABSTRACT**

Housing with directed-flow cooling (10) for computer (110) provides auxiliary airflow for cooling a heat-sensitive component, such as CPU (120). Housing (10) includes partition (60) that separates housing (10) into a lower compartment (40) for enclosing computer (110) and an upper compartment (20) for receiving ambient air through slots (24). Partition (60) includes vent opening (61) above CPU (120) that allows air to flow from upper compartment into CPU (120), directed by impingement fan (50).

**12 Claims, 3 Drawing Sheets**

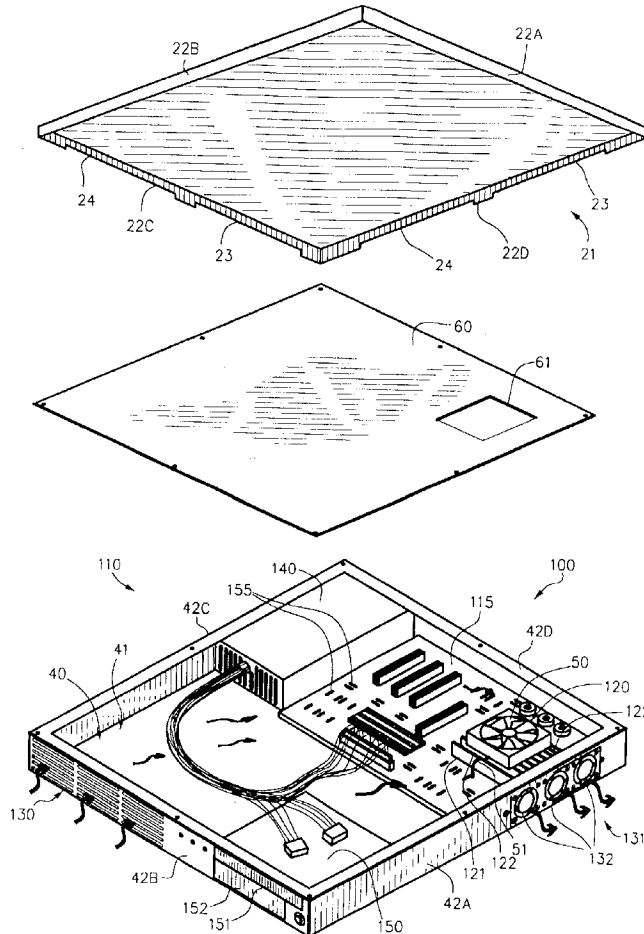


FIG. 1

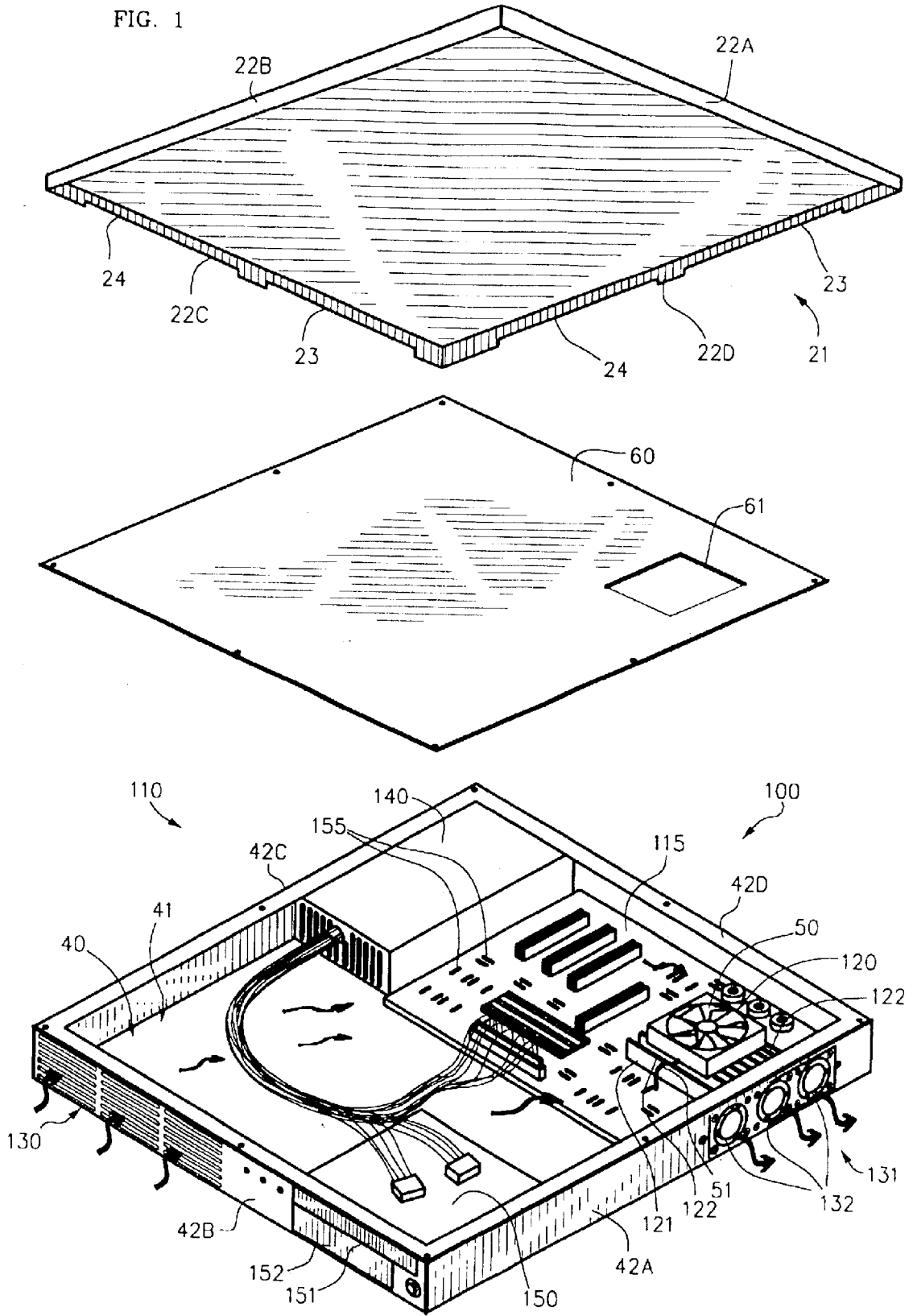


FIG. 7

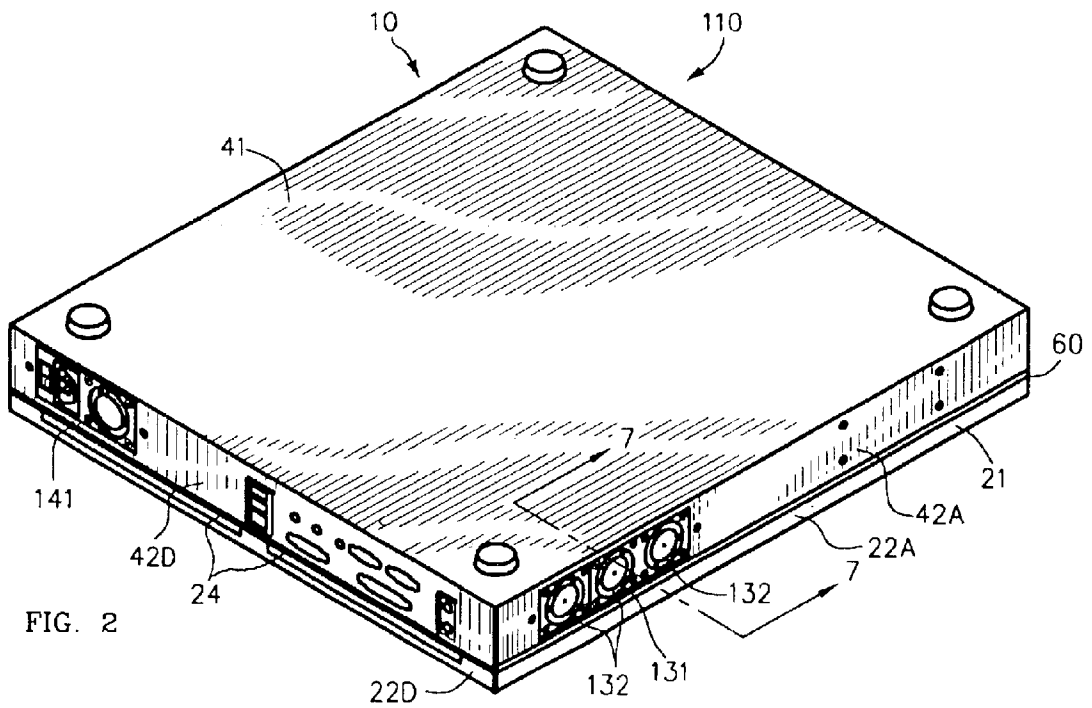
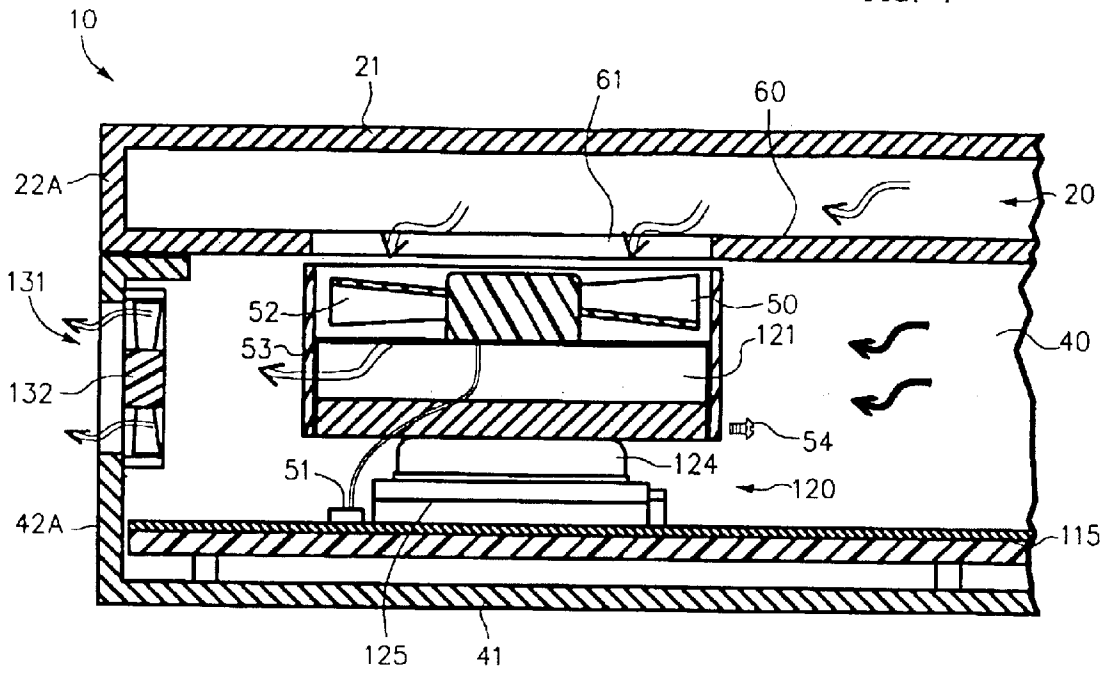
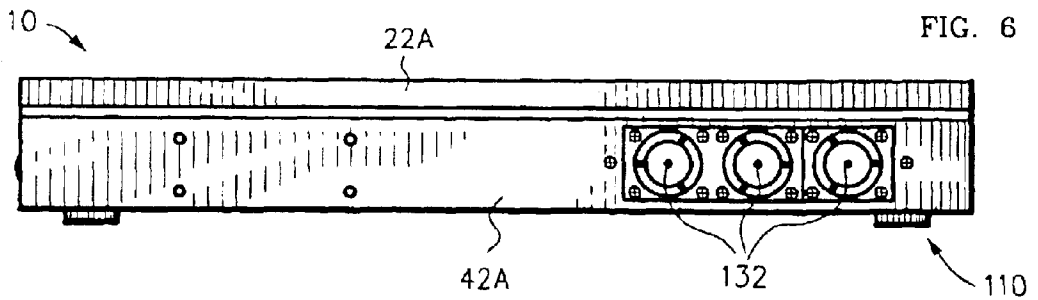
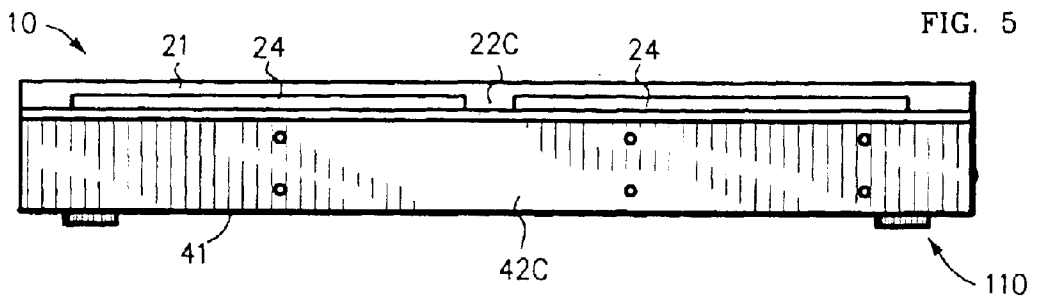
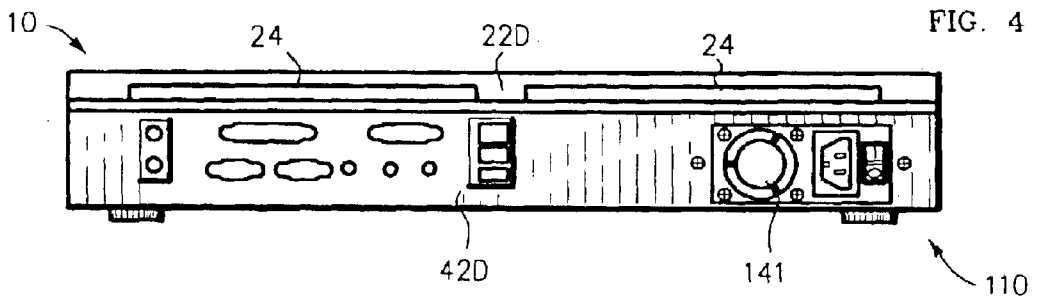
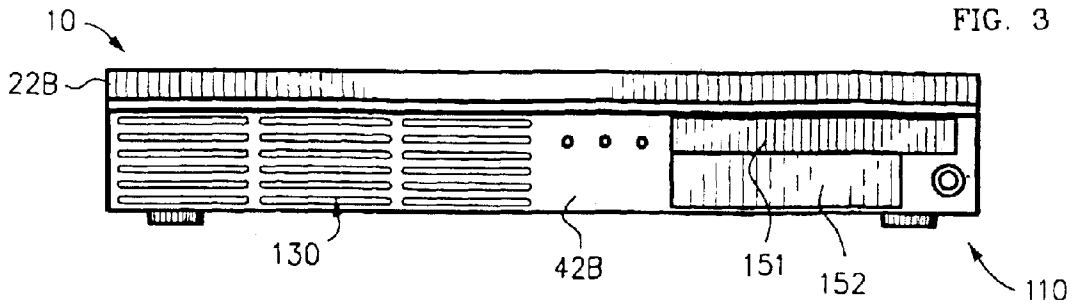


FIG. 2



## HOUSING WITH DIRECTED-FLOW COOLING FOR COMPUTER

### FIELD OF THE INVENTION

This invention relates to a housing for a computer that enhances processor cooling by ambient air and more specifically to a partition, vent, and fan system that causes cooling air to impinge first upon the most heat-sensitive component of the computer.

### BACKGROUND OF THE INVENTION

Low profile, rack mountable, electronic devices, such as computers and servers, contain heat-generating components that are particularly heat sensitive, that is, they operate poorly or fail to operate if they are above a certain temperature. The central processing unit (CPU) is typically one such device.

Most conventional CPUs are cooled by providing a flow path for air through the housing of the device and an internal fan for moving the air along the path and over the CPU. The air received by the CPU has typically already been heated by other components in the device, such that the cooling performance of the air on the CPU is somewhat dependent upon the heat generated by components upstream in the flow path. CPU operation may be adversely affected by adding heat-generating components upstream or by driving the upstream components to higher power consumption.

Typically, cooling air is drawn in through an air intake grille in the front of the housing and exhausted through an outlet in the back or side of the housing. Although it is preferable that the heat-sensitive components are located nearest the grille, it is not always possible. For example, it is often necessary to mount input-output devices, such as CD-ROM or tape drives, near the front of the housing so that they are accessible to the user. In some cases, the most heat-sensitive component may have to be mounted far from the air intake grille.

The problem is exacerbated in very low profile devices, such as rack mountable devices, where there is high density of components and limited space for cooling air flow path.

Therefore, there has been a need to provide improved cooling to an electronic device having a particularly heat-sensitive component, particularly to a low profile rack-mountable computer.

### SUMMARY OF THE INVENTION

The present invention is a housing for a computer or similar electronic device with both heat-generating and heat-sensitive components, and for which the standard air cooling is not sufficient.

The housing is separated by a partition into a lower compartment, enclosing the electronic components, and an upper compartment for receiving cooling air for the heat-sensitive component, such as the CPU. The partition includes a vent that allows cool air to flow from the upper compartment and impinge upon the CPU without first passing over heat-generating components. A fan for moving the cooling air may be attached to the top of the CPU, such as by mounting onto the CPU heatsink.

The upper compartment includes air inlets for receiving ambient air. Typically, CPU cooling airflow joins the standard airflow from the front grille and exits the housing via an exhaust outlet near the rear of the housing. An additional advantage of providing air inlets near the cover of the

device, in the case of a desktop computer, is that the inlets are less likely to be blocked accidentally by other items.

A computer may be initially provided with this housing with enhanced cooling, or a standard computer enclosure may be retro-fitted by addition of a partition with vent inside the standard enclosure so as to separate the enclosure into compartments

### BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is an exploded perspective view of the computer housing and directed air flow cooling system of the invention. Lower compartment **40** and partition **60** are seen from above; upper compartment **20** is seen to be in condition for allowance and allowance is requested from below.

FIG. 2 is a right side, rear, bottom perspective view thereof.

FIG. 3 is a front elevation view thereof.

FIG. 4 is a rear elevation view thereof.

FIG. 5 is a left side view thereof.

FIG. 6 is a right side view thereof.

FIG. 7 is a partial sectional view taken on line 7—7 of FIG. 1 and inverted.

### DETAILED DESCRIPTION OF THE INVENTION

With reference now to the drawings, and more particularly to FIGS. 1 and 7 thereof, there is shown a housing **10** for an electronic device **100**, such as rack-mountable computer **110**. FIG. 1 is an exploded perspective view of computer housing **10** and directed air flow cooling system of the invention. FIG. 7 is a partial sectional view taken on line 7—7 of FIG. 1.

Computer **110** includes many heat-generating components **155**, such as resistors, capacitors, and memory chips, and at least one heat-sensitive component, such as CPU **120**, mounted upon a circuit board **115**. Computer **110** also includes a power supply **140**, which has its own cooling fan **141** (seen in FIG. 4), and an input/output device such as CD-ROM drive **150** accessible to the user through access door **151**. A hard disk memory is mounted behind panel **152** and underneath CD-ROM drive **150**.

The components of computer **110** are mounted in lower compartment **40** of housing **10**. Lower compartment **40** includes floor **41**, which supports circuit board **115** and other components of computer **110**, and lower sidewalls **42** attached to the edges of floor **41** and extending upward to define lower compartment **40**. In the preferred embodiment illustrated in FIG. 1, lower compartment **40** includes four lower sidewalls: first lower sidewall **42A**, second lower sidewall **42B**, third lower sidewall **42C**, and fourth lower sidewall **42D**, which are attached to floor **41** and to each other to define a rectangular lower compartment **40**.

In the preferred embodiment illustrated in FIG. 1, lower compartment **40** includes the elements of conventional air cooling: an air intake grille **130** and exhaust fans **132** mounted vertically within exhaust outlet **131**. Fans **132** draw warm air from inside lower compartment **40**, causing cool ambient air to flow into air intake grille **130**. To minimize recirculation of warm air, exhaust outlet **131** is located toward the rear of first lower sidewall **42A** and air intake grille **130** is located diagonally opposite on the left end of lower second sidewall **42B**.

In the preferred embodiment shown in the drawings, airflow in the conventional cooling system is from air intake

grille **130** to exhaust outlet **131** and is indicated figuratively by black arrows. As can be seen in FIG. 1, cooling air passes over heat-generating components **155** before reaching heat-sensitive CPU **120**. Because the air has been warmed by heat-generating components **155**, it has less capacity to cool CPU **120**. CPU **120** may thus overheat and malfunction.

In a conventional computer housing, lower compartment **40** would be covered by a solid panel (not shown), such as a metal sheet. In the case of computer housing **10** and directed air flow cooling system of the present invention, lower compartment **40** is covered by partition **60**, which includes vent opening **61**. When partition **60** is in place upon lower compartment **40**, vent opening **61** is located directly above CPU **120**.

Partition **60** is covered by cover **21**. Upper sidewalls **22** are attached to the edges of cover **21** and extend downward, defining an upper compartment **20**. Partition **60** generally separates upper compartment **20** from lower compartment **40**, with communication through vent opening **61**.

Upper compartment **20** includes four upper sidewalls **22** in the preferred embodiment depicted: first upper sidewall **22A**, second upper sidewall **22B**, third upper sidewall **22C**, and fourth upper sidewall **22D**, which are attached to cover **21** and to each other to define a rectangular upper compartment **20**.

At least one upper sidewall **22**, such as third upper sidewall **22C**, includes one or more air inlets **23**, such as slots **24**, for receiving ambient air into upper compartment **20**. To avoid recirculation of warm air that has been exhausted from exhaust outlet **131**, it is generally preferred that first upper sidewall **22A** not include slots **24**.

Partition **60**, if used without a cover **21**, would not provide sufficient environmental and mechanical protection to computer **110**. A liquid spilled above partition **60** could penetrate into housing **10**. Cover **21** and slots **24** allow air to pass easily to vent opening **61**, but prevent all but a forcefully sprayed liquid from entering lower compartment **40**.

The action of conventional exhaust fans **132** located in exhaust opening **131** draws ambient air into upper compartment **20** via slots **24** and downward through vent opening **61**, as indicated figuratively by white arrows in FIG. 7. The additional source of non-preheated air flowing over CPU **120** helps prevent CPU **120** from overheating. However, this additional flow is largely laminar in nature and may not contact CPU **120** fully before exiting through exhaust outlet **131**.

To maximize the cooling efficiency of the auxiliary airflow, an impingement fan **50** directs the auxiliary cooling airflow from upper compartment **20** to impinge forcefully in a turbulent manner onto CPU **120**. In the partial sectional view of FIG. 7, CPU **120** is depicted as including device package **124**, mounted in a mount, such as socket **125** attached to circuit board **115**. CPU **120** includes a heatsink **121**, which is thermally conductive and is heated by CPU **120**. Heatsink **121** includes fins **122** for radiating heat to the auxiliary airflow, indicated figuratively by white arrows, that flows around fins **122**. Fins **122**, seen in side view in FIG. 7, generally comprise a plurality of thin, elongate members of thermally conductive material, such as copper, with channels between individual fins for passage of cooling air.

In FIG. 7, impingement fan **50** is shown mounted above fins **122** of heatsink **121**. Impingement fan **50** includes impellers **52** and shroud **53**. Impingement fan **50** is mounted above fins **122** by means of a screw **54** attaching shroud **53** to heatsink **121**. Impingement fan **50** draws cooling air from upper compartment **20** and forces it turbulently against fins

**122**. After contacting fins **122** and cooling them, the auxiliary airflow joins with the conventional cooling airflow and exits lower compartment **40** via exhaust outlet **131**.

Impingement fan **50** is powered by fan activation means **51**. Fan activation means **51** is a circuit that includes a thermocouple (not shown) that closes the circuit to activate impingement fan **50** when the temperature in the vicinity of CPU **120** exceeds a pre-set value. Alternatively, impingement fan **50** may be designed so as to be activated whenever computer **110** is operating.

FIG. 2 is a right side, rear, bottom perspective view of housing **10** for computer **110**. FIG. 3 is a front elevation view of housing **10**. FIG. 4 is a rear elevation view of housing **10**. FIG. 5 is a left side view of housing **10**. FIG. 6 is a right side view of housing **10**.

Having described the preferred embodiment of the invention, many alterations and modifications which are within the inventive concepts disclosed herein will likely occur to those skilled in the art.

For example, impingement fan **50** may be mounted elsewhere than above heatsink **121**. Alternatively, impingement fan **50** may be mounted within vent opening **61** such that auxiliary airflow is directed downward onto heatsink **121**. Alternatively, impingement fan **50** may be mounted on the inner face of cover **21** such that airflow is directed downward through vent opening **61**.

Housing **10** may be of various shapes, such as will be appropriate for containing an electronic device **100** or for being mounted in a rack (not shown) of a given size. The outside shape may be rectangular, square, or any other appropriate shape. As noted above, air inlet(s) **23** may be located at various points on upper sidewalls **22**, but it is generally preferred that air inlet(s) **23** be located far enough from exhaust outlet **131** that warm air is not recirculated into housing **10**.

Alternatively to the embodiment illustrated, housing **10** may be designed without air intake grille **130**, such that all cooling airflow is received through air inlet(s) **23** and delivered to lower compartment **40** through vent opening **61**, particularly if there is only one heat-sensitive component **120**.

Therefore, it is to be understood that all matter herein is to be interpreted as illustrative and not in any limiting sense, and it is intended to cover in the appended claims such modifications as come within the true spirit and scope of the invention.

I claim:

1. A housing for an electronic device that includes a plurality of components, at least one being a heat-generating component and at least one being a heat-sensitive component; said housing including:

a partition separating said housing into two compartments; said compartments comprising:

a lower compartment for enclosing the heat-generating and heat-sensitive components; including:

an air intake grille for receiving ambient air into said lower compartment;

a floor for supporting components of the electronic device; and

side walls connected to the edges of said floor and extending upward; including:

an exhaust outlet for allowing hot air to flow out of said lower compartment; including an exhaust fan for directing warm air out of said exhaust outlet; wherein said plurality of heat-generating components are between said air intake grille and said exhaust outlet and

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an upper compartment for receiving ambient air; including  
 a cover;  
 side walls connected to the edges of said cover and extending downward; including:  
 an air inlet for admitting ambient air into said upper compartment; and  
 an impingement fan; and wherein said partition includes a vent opening located near the heat-sensitive component for allowing cool air to flow from said upper compartment onto the heat-sensitive component; and said impingement fan impels cool air to move through said vent opening toward said heat-sensitive component.

2. The housing of claim 1, wherein said fan is attached to the top of the heat-sensitive component and pulls air downward onto the heat-sensitive component.

3. The housing of claim 2, further including fan activation means for activating said fan when the temperature of heat-sensitive component exceeds a pre-set value.

4. The housing of claim 1, wherein both said compartments include four side walls and are rectangular in shape; and wherein said air inlet for admitting ambient air into said upper compartment comprises a plurality of openings spaced apart on said side wall that is opposite the side wall that includes said vent outlet.

5. In combination:  
 an electronic device including:  
 a plurality of heat-generating components; and  
 a heat-sensitive component; and  
 a housing for said electronic device; including:  
 a lower compartment for enclosing said plurality of heat-generating components; including:  
 a floor;  
 a first side wall; including  
 an exhaust outlet for allowing hot air to flow out of said enclosure;  
 a second side wall;  
 a third side wall; and  
 a fourth side wall; said side walls connected to each other and extending upward from the perimeter of said floor so as to define a rectangular, open-topped box;

an upper compartment for receiving ambient air; including:  
 a cover,  
 a first side wall;  
 a second side wall;  
 a third side wall; and  
 a fourth side wall; said side walls connected to each other and extending downward from the perimeter of said cover so as to define a rectangular, open-bottomed box; at least one of said side walls including:  
 an air inlet for admitting ambient air into said upper compartment; and  
 a partition separating said lower compartment from said upper compartment; including:  
 a vent opening located near said heat-sensitive component for allowing cool air to flow from said

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upper compartment onto said heat-sensitive component; and:  
 an impingement fan for directing cooling air from said upper compartment onto said heat-sensitive component.

6. The combination of claim 5, said lower compartment further including an air intake grille for receiving ambient air into said lower compartment; and said exhaust outlet including an exhaust fan for directing warm air out of said exhaust outlet; and wherein said plurality of heat-generating components are between said air intake grille and said exhaust outlet.

7. An electronic device including:  
 walls defining an enclosure including:  
 a floor;  
 a cover; and  
 side walls; and  
 a partition between said top wall and said bottom wall dividing said enclosure into lower and upper compartments;  
 a plurality of heat generating electric components mounted in said lower compartment of said enclosure including:  
 a heat sensitive processing unit;  
 a heatsink mounted on said processing unit;  
 a main cooling system comprising:  
 an air intake grille in one said side wall for entry of air into said lower compartment;  
 a first exhaust outlet in one said side wall for outlet of air from said lower compartment;  
 a first fan connected to said enclosure for moving air from said air intake grille, past said plurality of electric components, and to said exhaust outlet so as to cool said electronic components; and  
 an auxiliary cooling system comprising:  
 an air inlet in one said side wall for entry of air into said upper compartment;  
 a vent opening in said partition for exit of air from said upper compartment substantially directly on said heatsink;  
 a second fan mounted in said enclosure for moving air from said air inlet of said auxiliary cooling system, through said vent opening of said auxiliary cooling system, and onto said heatsink.

8. The electronic device of claim 7, wherein said air inlet is in one said side wall opposite said exhaust outlet.

9. The electronic device of claim 8, wherein said second fan is mounted on said heatsink.

10. The electronic device of claim 9, further including:  
 fan activation means for activating said second fan when the temperature of said heat sensitive processing unit exceeds a pre-set value.

11. The electronic device of claim 7 wherein said second fan is mounted on said heatsink.

12. The electronic device of claim 11 further including:  
 fan activation means for activating said second fan when the temperature of said heat sensitive processing unit exceeds a pre-set value.

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